VERY THIN MULTI-CHIP-PACKAGE AND METHOD OF MASS PRODUCING THE SAME

ABSTRACT OF THE DISCLOSURE

A substrate assembly and method of forming the substrate assembly having a very thin form factor and a large amount of manufacturing flexibility. A flexible tape has a number of device blocks. Devices, passive or active, are joined to the device blocks forming a flexible tape assembly and the flexible tape assembly is electrically tested. Substrates are formed having cavities matching the device blocks. The flexible tape assembly is then joined to the substrate such that the devices fit into the cavities, thereby forming a substrate assembly having a very thin form factor. The flexible tape can be stored on a reel and the substrates can be formed in an array and cut to the desired size providing manufacturing flexibility.

(Fig. 1a)

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